

ABSTRACT of JP 2002-100869

**PROBLEM TO BE SOLVED:** To provide a circuit board together with its manufacturing method which is useful for manufacturing a multilayer circuit board for less thickness and for multiple layers.

**SOLUTION:** A circuit board A1 is sequentially laminated on a lower-layer circuit board A0. Related to the circuit board A1, a solid columnar conductor 13 is provided in a through hole 11 opened in a fiber reinforced resin substrate 10, and a resin cured layer 14 is present between an inside wall surface 11a of the through hole 11 and an outside perimeter 13a of the columnar conductor 13, with at least the upper surface of the columnar conductor 13 covered with a conductive thin layer 15.